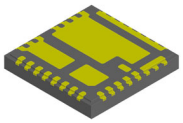
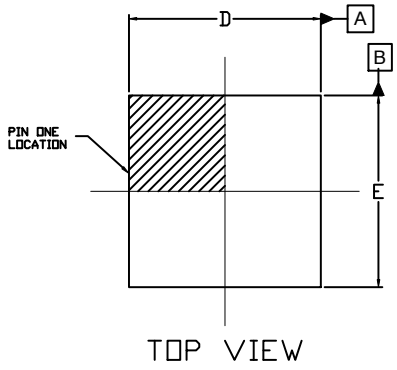


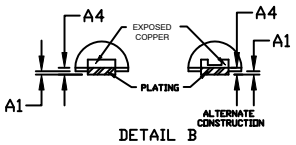
WQFNW31, 5x5, 0.5P
CASE 512AE
ISSUE B

DATE 01 JUN 2021

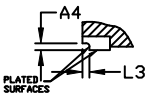


TOP VIEW

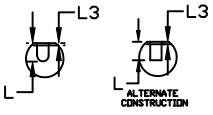
NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.



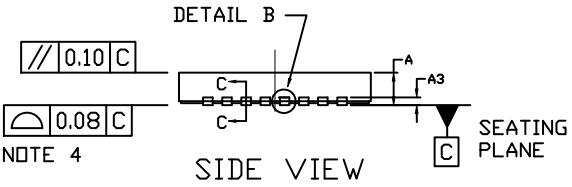
DETAIL B



SECTION C-C

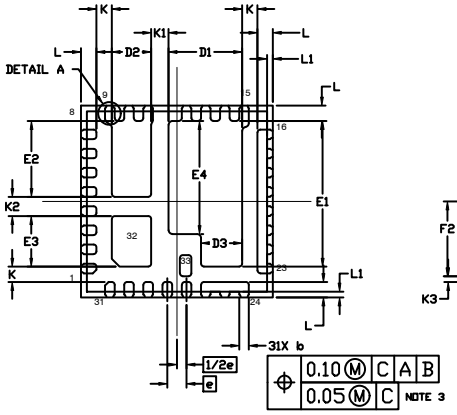


DETAIL A

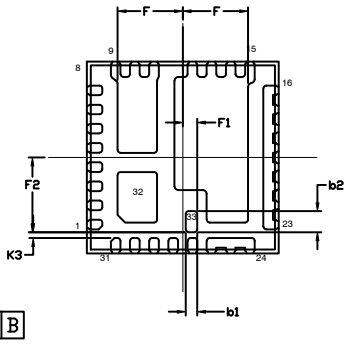


SIDE VIEW

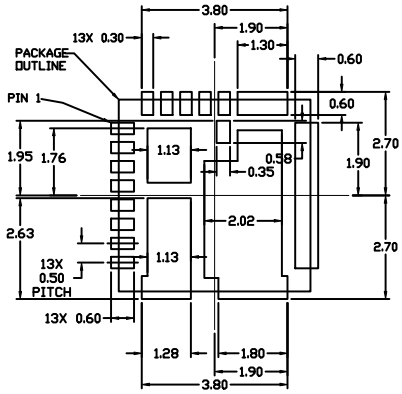
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.70	0.75	0.80
A1	---	---	0.05
A3		0.20 REF	
A4	0.10	---	---
b	0.20	0.25	0.30
b1	0.25	0.30	0.35
b2	0.50	0.55	0.60
D	4.90	5.00	5.10
D1	1.82	1.92	2.02
D2	0.93	1.03	1.13
D3	0.93	1.03	1.13
E	4.90	5.00	5.10
E1	3.70	3.80	3.90
E2	1.88	1.98	2.08
E3	1.22	1.32	1.42
E4		2.95 REF	
e		0.50 BSC	
K		0.40 REF	
K1		0.45 REF	
K2		0.50 REF	
K3		0.15 REF	
L	0.30	0.40	0.50
L1		0.15 REF	
L3	---	---	0.10
F		1.70 REF	
F1		0.375 REF	
F2		1.95 REF	



BOTTOM VIEW



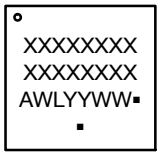
BOTTOM VIEW
(ADDITIONAL DETAIL)



RECOMMENDED
MOUNTING FOOTPRINT

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
▪ = Assembly Lot

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	**WQFNW31, 5x5, 0.5P**	**PAGE 1 OF 1**